WAFER PROCESSING METHOD

ABSTRACT

Disclosed herein is a wafer processing method of dividing a wafer along a plurality of crossing division lines to obtain a plurality of individual devices. The division lines are formed on the front side of the wafer to thereby define a plurality of separate regions where the respective devices are formed. The wafer processing method includes a wafer supporting step of mounting one side of an adhesive film on the back side of the wafer and attaching the other side of the adhesive film to a dicing tape composed of a base sheet and an ultraviolet curable adhesive layer formed on the base sheet, the adhesive film being attached to the ultraviolet curable adhesive layer of the dicing tape, an ultraviolet light applying step of applying ultraviolet light to the dicing tape to thereby cure the adhesive layer after performing the wafer supporting step, and a cutting step of rotating a cutting blade having a peripheral cutting edge to cut the wafer together with the adhesive film along the division lines after performing the ultraviolet light applying step, thereby dividing the wafer into the individual devices. The cutting edge of the cutting blade is positioned so that the cutting edge cuts into the cured adhesive layer in the cutting step.

(Figure 6 C)